

**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hiroyuki KUMAKURA

Group Art Unit: 2841

Application No.: Rule 53(b) Divisional Application of  
U.S. Application No. 09/603,840

Examiner: I. Patel

Filed: November 26, 2001

Docket No.: 106589.01

For: METHOD FOR CONNECTING ELECTRICAL COMPONENTS (AS AMENDED)

**PRELIMINARY AMENDMENT**

Director of the U.S. Patent and Trademark Office  
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

**IN THE TITLE:**

Please replace the title as follows:

METHOD FOR CONNECTING ELECTRICAL COMPONENTS

**IN THE CLAIMS:**

Please replace claim 2 as follows:

2. (Amended) A connection method, comprising:

electrically connecting first electrodes on a first substrate and second electrodes on a second substrate with an interposed anisotropic electroconductive adhesive layer, wherein the thickness of the electroconductive adhesive layer prior to connection is given by:

$$0.5 \times \{(A^1 C^1 + A^2 C^2) / (B+C)\} \leq X \leq 2 \times \{(A^1 C^1 + A^2 C^2) / (B+C)\}$$

where: